L Number	Hits	Search Text	DB	Time stamp
-	211	((wire or wiring) near5 (short or shorten or	USPAT;	2004/02/21
		shortening or shorter)) and electrode.clm.	US-PGPUB;	09:44
		and (wire or wiring).clm. and ((first or	EPO; JPO;	
		second or upper or lower or top or bottom)	DERWENT;	
		near3 (chip or ic)).clm.	IBM_TDB	
_	3	((wire or wiring) near5 (short or shorten or	USPAT;	2004/02/21
-	3	shortening or shorter)) and electrode.clm.	US-PGPUB;	09:44
		and (wire or wiring).clm. and ((first or	EPO; JPO;	05.44
		second or upper or lower or top or bottom)	DERWENT;	
		,	IBM_TDB	
	44	near3 (chip or ic)).clm. and interposer.clm.	_	2004/02/21
-	11	((wire or wiring) near5 (short or shorten or	USPAT;	
		shortening or shorter)) and electrode.clm.	US-PGPUB;	09:46
		and (wire or wiring).clm. and ((first or	EPO; JPO;	
		second or upper or lower or top or bottom)	DERWENT;	
		near3 (chip or ic)).clm. and interposer	IBM_TDB	
-	42	((wire or wiring) near5 (short or shorten or	USPAT;	2004/02/21
		shortening or shorter)) and electrode.clm.	US-PGPUB;	09:49
		and (wire or wiring).clm. and ((first or	EPO; JPO;	
		second or upper or lower or top or bottom)	DERWENT;	
		near3 (chip or ic) near5 (back or reverse or	IBM_TDB	
		opposite)).clm.		
-	21	((wire or wiring) near5 (short or shorten or	USPAT;	2004/02/21
		shortening or shorter)) and electrode.clm.	US-PGPUB;	09:51
		and (wire or wiring).clm. and ((first or	EPO; JPO;	
		second or upper or lower or top or bottom)	DERWENT;	
		near3 (chip or ic) near5 (back or reverse or	IBM_TDB	
		opposite)).clm. and (stack or stacking or		
		stacked)		
-	121	((hole or opening) same ((first or second or	USPAT;	2004/02/21
		upper or lower or top or bottom) near3 (chip	US-PGPUB;	09:54
		or ic)) same (wire or wiring) same electrode	EPO; JPO;	
1		same (back or reverse or opposite))	DERWENT;	
			IBM_TDB	
-	22	((hole or opening) same ((first or second or	USPAT;	2004/02/21
		upper or lower or top or bottom) near3 (chip	US-PGPUB;	09:56
		or ic)) same (wire or wiring) same electrode	EPO; JPO;	
		same (back or reverse or opposite)).clm.	DERWENT;	
		, , , , , , , , , , , , , , , , , , , ,	IBM_TDB	
_	29	((hole or opening) same ((first or second or	USPAT;	2004/02/21
:		upper or lower or top or bottom) near3 (chip	US-PGPUB;	10:19
		or ic)) same (wire or wiring) same electrode	EPO; JPO;	
		same (back or reverse or opposite)) and	DERWENT;	
		((wire or wiring) near3 (short or shorten or	IBM_TDB	
		shorter or shortening))		
_	41	interposer.clm. and electrode.clm. and	USPAT;	2004/02/21
-	71	(wire or wiring).clm.	US-PGPUB;	10:20
		(wite of withing).cim.	1	10:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	

	6	interposer.clm. and electrode.clm. and	USPAT;	2004/02/21
-		(wire or wiring).clm. and (stack or stacking	US-PGPUB;	10:20
		or stacked).clm.	EPO; JPO;	10.20
		or stacked).cim.	1 '	
			DERWENT;	
			IBM_TDB	0004/00/04
-	14	interposer.clm. and electrode.clm. and	USPAT;	2004/02/21
		(wire or wiring).clm. and (stack or stacking	US-PGPUB;	10:26
		or stacked)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	. 4	((nonconducting or nonconductive or	USPAT;	2004/02/21
		non-conducting or non-conductive) near	US-PGPUB;	10:25
		interposer).clm.	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	13582	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm.	US-PGPUB;	10:27
		,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
1_	273	((first or second or upper or lower or top or	USPAT;	2004/02/21
-	2/3	bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:27
		or stacked or stacking) and electrode.clm.	EPO; JPO;	10.27
		•		
		and (wire or wiring).clm.	DERWENT;	
	400	<i>115</i> 4	IBM_TDB	2004/00/04
-	122	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:28
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm.	IBM_TDB	
-	4937	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:28
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
]	opening or through-hole).clm. interposer	IBM_TDB	
-	2	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:29
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		interposer		
_	79	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:29
	[or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		(interposer or glass)		
_	15	((first or second or upper or lower or top or	USPAT;	2004/02/21
-	'3	bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:29
			1	14124
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		(interposer or glass).clm.		

r			HODAT	2004/00/04
-	44	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:30
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		(interposer or glass or tape).clm.		
-	0	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:30
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		((nonconducting or non-conducting or		
		nonconductive or non-conductive) near		
		(interposer or glass or tape)).clm.		
-	0	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:30
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
	'	and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		((nonconducting or non-conducting or	_	
		nonconductive or non-conductive) near		
		(interposer or glass or tape))		
_	o	((first or second or upper or lower or top or	USPAT;	2004/02/21
		bottom) near3 (chip or ic)).clm. and (stack	US-PGPUB;	10:31
		or stacked or stacking) and electrode.clm.	EPO; JPO;	
		and (wire or wiring).clm. and (hole or	DERWENT;	
		opening or through-hole).clm. and	IBM_TDB	
		((nonconducting or non-conducting or		
		nonconductive or non-conductive) near5		
		(interposer or glass or tape))		
_	1 1	((first or second or upper or lower or top or	USPAT;	2004/02/21
	<u>-</u>	bottom) near3 (chip or ic)).clm. and	US-PGPUB;	10:31
		electrode.clm. and (wire or wiring).clm. and	EPO; JPO;	10.01
		(hole or opening or through-hole).clm. and	DERWENT;	
		((nonconducting or non-conducting or	IBM_TDB	
		nonconductive or non-conductive) near5	.51.56	
		(interposer or glass or tape))		
_	80	((first or second or upper or lower or top or	USPAT;	2004/02/21
-	60	(tirst or second or upper or lower or top or bottom) near3 (chip or ic)).clm. and	US-PGPUB;	10:31
		electrode.clm. and (wire or wiring).clm. and	EPO; JPO;	19.51
		(hole or opening or through-hole).clm. and	DERWENT;	
		((interposer or glass or tape)).clm.	IBM_TDB	
_	29		. –	2004/02/21
-	29	((first or second or upper or lower or top or	USPAT; US-PGPUB;	10:32
		bottom) near3 (chip or ic)).clm. and	· ·	IVIJZ
		electrode.clm. and (wire or wiring).clm. and	EPO; JPO;	
		(hole or opening or through-hole).clm. and	DERWENT;	
		((interposer or glass or tape)).clm. and	IBM_TDB	
		(electrode same (wire or wiring) same (chip		
		or ic) same (hole or opening or		
		through-hole) same (interposer or glass or		
	<u> </u>	tape))		

	21	((first or second or upper or lower or top or	USPAT;	2004/02/21
1		bottom) near3 (chip or ic)).clm. and	US-PGPUB;	10:37
		electrode.clm. and (wire or wiring).clm. and	EPO; JPO;	
		(hole or opening or through-hole).clm. and	DERWENT;	
		((interposer or glass or tape)).clm. and	IBM_TDB	
		(electrode same (wire or wiring) same (chip		
		or ic) same (hole or opening or		
		through-hole) same (interposer or glass or		
		tape)).clm.		